



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-05
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MFWV*NK03FC3	A	Z8GA	2015-06-05
Amount	UoM	Unit type	ST ECOPACK Grade	
17.25	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.82X1.52X1.25	5	gull wing	
Comment	Package: SOT23 5L; MDF valid for LD2985BM30R			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MFWV*NK03FC3					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.963	mg		Silicon die	Silicon (Si)	7440-21-3		0.928		963655	53791
						Aluminium (Al)	7429-90-5		0.015		15576	869
						Silicon Nitride (SiN)	68034-42-4		0.004		4154	232
						Silicon Oxide(SiO2)	7631-86-9		0.008		8307	464
						Gamma-butyrolactone	96-48-0		0.006		6231	348
						Polyhydroxyamide	55295-98-2		0.002		2077	116
Leadframe	Copper & its alloys	6.188	mg		Alloy	Copper(CU)	7440-50-8		6.029		974305	349467
						Iron(Fe)	7439-89-6		0.146		23594	8463
						Iron Phosphide (FeP)	26508-33-8		0.005		808	290
						Zinc(Zn)	7440-66-6		0.008		1293	464
Leadframe coating	Precious metals	0.155	mg		coating	Silver(Ag)	7440-22-4		0.155	1000000	8984	
Die attach	Other Organic Materials	0.192	mg		Glue	Silver (Ag)	7440-22-4		0.156		812500	9042
						Acrylate resins	7534-94-3		0.023		119792	1333
						Heterocyclic organic compound	3006-93-7		0.006		31250	348
						Fluoroaliphatic Polymeric Esters	1017237-78-3		0.001		5208	58
						Treated silica	Proprietary		0.006		31250	348
Bonding wire	Precious metals	0.667	mg		Bonding wire	Gold(Au)	7440-57-5		0.667	1000000	38662	
Encapsulation	Other Organic Materials	8.885	mg		Molding compound	Fused Silica	60676-86-0		6.931		780079	401751
						Solid Epoxy Resin	85954-11-6		0.977		109961	56631
						Phenol Resin	26834-02-6		0.977		109961	56631
Finishing	Other inorganic materials	0.202	mg		Connections coating	Tin(Sn)	7440-31-5		0.202	1000000	11709	